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Attorney Docket No. 108298633US

Disclosure No. 01-0389

INFORMATION DISCLOSURE
STATEMENT BY APPLICANTForm PTO-1449 (Modified)
(Use several sheets if necessary)

COMPLETE IF KNOWN

Application Number	10034/924
Confirmation Number	1417
Filing Date	December 26, 2001
First Named Inventor	Stephen Moxham
Group Art Unit	2826
Examiner Name	Alexander O. Williams
Attorney Docket No	108298633US

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U.S. PATENT DOCUMENTS

Examiner Initials*	Cite No.	U.S. Patent or Application		Name of Patentee or inventor of Cited Document	Date of Publication or Filing Date of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
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EXAMINER

DATE CONSIDERED

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Examiner Initials*	Cite No.	Foreign Patent or Application		Name of Patentee or Applicant of Cited Document	Date of Publication or Filing Date of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T
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